VLINK
An AFR Company

Vlink Optics Corporation

High-Precision FAU for CPO & Silicon Photonics Interconnects

Description

Vlink's CPO FAU (Co-Packaged Optics Fiber Array Unit) Connectivity series is engineered to address the critical bottlenecks in Ultra-High-Bandwidth AI and Hyperscale Data Center networks. As the industry transitions to 51.2T and 102.4T switching capacities, our FAU solutions provide the essential bridge between Photonic Integrated Circuits (PICs) and external fiber networks. Designed with Industry-Leading precision, Vlink ensures minimal insertion loss and maximum reliability for co-packaged architectures.

Key Features

- Ultra-Precise Core Pitch Control
- Advanced MFD Matching
- High-Density & Low-Profile Design
- Specialty Fiber Integration
- Robust Reliability

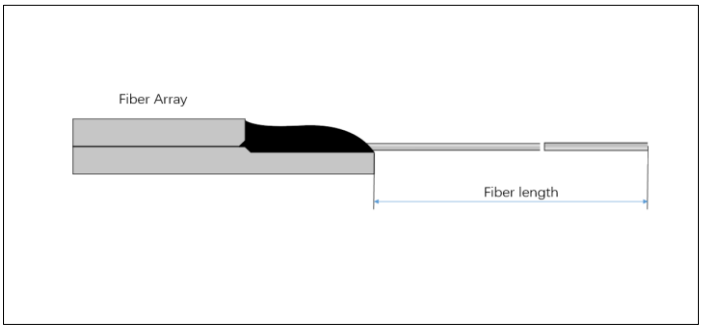
Applications

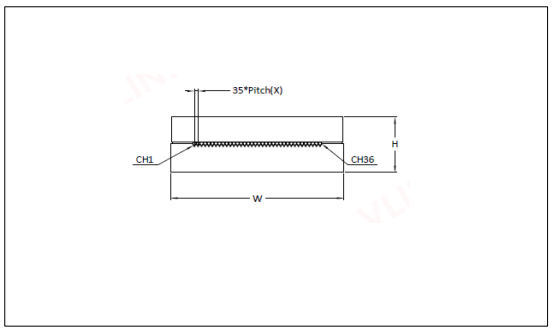
- CPO (Co-Packaged Optics)
- AI/ML Clusters and GPU-to-GPU Interconnects
- Silicon Photonics (SiPh) Chip-Level Packaging
- High-Performance Computing (HPC) Architectures

Specifications

Parameter	Unit	Value
Wavelength	nm	1310
Fiber Count	-	8 ch, 16 ch, 32 ch,40 ch, 80 ch + (Customizable)
Max. Connector Insertion Loss	dB	0.5
Max. Coupling Insertion Loss	dB	1.0
Min. Return Loss	dB	30.0
Min. PER	dB	20.0
Fiber Pitch Spacing	μm	84 μm,127 μm, 250 μm (Customizable)
Max. Core Pitch Error	μm	± 0.7
Fiber Type	-	SM (G.657.A1/A2), PM Fiber, RCBI (Reduced-Clad)
Termination Connector Type	-	LC, FC, MPO, MMC, ELSFP Connector (Customizable)
Operating Temperature	°C	- 40 °C to + 85 °C

Package Dimensions





Ordering Information

FA-①①-②-③-④-⑤

①①: Fiber Count
08 - 8 Channel
16 - 16 Channel
40 - 40 Channel
S - Specify

②: Fiber Pitch Spacing
1 - 84 μm
2 - 127 μm
3 - 250 μm
SS - Specify

③: Fiber Type
F - SM Fiber
P - PM Fiber
R - RCBI Fiber
S - Specify

④: Connector Type
N - None
S - Specify

⑤: Fiber Length
1 - 1 m
S - Specify